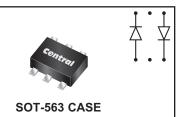
## CMLD6001DO

SURFACE MOUNT SILICON DUAL, ISOLATED, OPPOSING ULTRA LOW LEAKAGE SWITCHING DIODE





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# **DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CMLD6001DO type contains two (2) isolated opposing configuration, silicon switching diodes, manufactured by the epitaxial planar process, epoxy molded in an SOT-563 surface mount package. These devices are designed for switching applications requiring extremely low leakage.

**MARKING CODE: C60** 

MAXIMUM RATINGS: (T <sub>A</sub> =25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	$V_{R}$	75	V
Peak Repetitive Reverse Voltage	$V_{RRM}$	100	V
Continuous Forward Current	I <sub>F</sub>	250	mA
Peak Forward Surge Current, tp=1.0µs	<sup>I</sup> FSM	4.0	Α
Peak Forward Surge Current, tp=1.0s	<sup>I</sup> FSM	1.0	Α
Power Dissipation	$P_{D}$	250	mW
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
Thermal Resistance	$\Theta_{\sf JA}$	500	°C/W

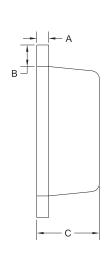
	CAL CHARACTERISTICS PER DIODE: TEST CONDITIONS V <sub>R</sub> =75V	(T <sub>A</sub> =25°C unles	s otherwise noted)  MAX  500	UNITS pA
$BV_R$	I <sub>R</sub> =100μA	100		V
$V_{F}$	I <sub>F</sub> =1.0mA		0.85	V
$V_{F}$	I <sub>F</sub> =10mA		0.95	V
$V_{F}$	I <sub>F</sub> =100mA		1.1	V
$C_J$	V <sub>R</sub> =0, f=1.0MHz		2.0	pF
t <sub>rr</sub>	$I_R = I_F = 10$ mA, $I_{rr} = 1.0$ mA, $R_L = 100$ $\Omega$		3.0	μs

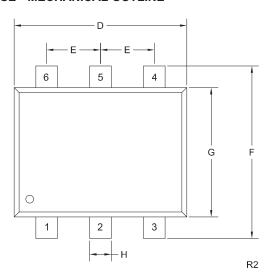
## CMLD6001DO

## SURFACE MOUNT SILICON DUAL, ISOLATED, OPPOSING ULTRA LOW LEAKAGE SWITCHING DIODE

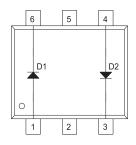


# **SOT-563 CASE - MECHANICAL OUTLINE**





## **PIN CONFIGURATION**



DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.0027	0.007	0.07	0.18			
В	0.008		0.20				
С	0.017	0.024	0.45	0.60			
D	0.059	0.067	1.50	1.70			
E	0.020		0.50				
F	0.059	0.067	1.50	1.70			
G	0.043	0.051	1.10	1.30			
Н	0.006	0.012	0.15	0.30			
SOT-563 (REV: R2)							

# LEAD CODE:

- 1) Anode D1
- 2) NC
- 3) Cathode D2
- 4) Anode D2
- 5) NC
- 6) Cathode D1

MARKING CODE: C60

R5 (15-June 2015)

### **OUTSTANDING SUPPORT AND SUPERIOR SERVICES**



#### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

### **DESIGNER SUPPORT/SERVICES**

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

### REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

### **CONTACT US**

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